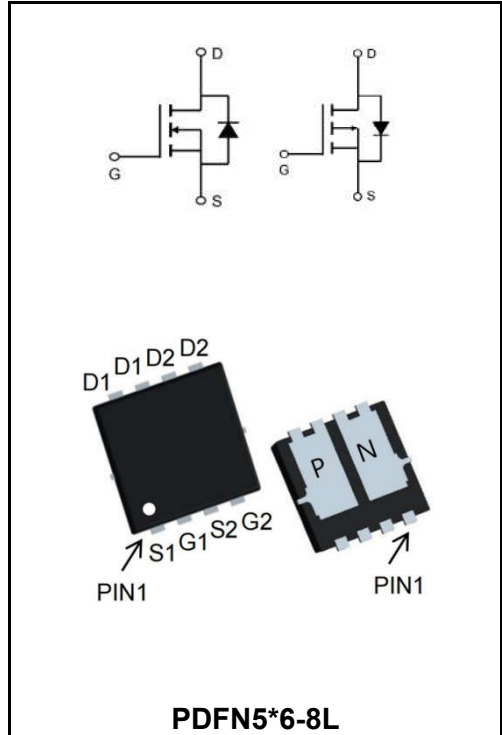


**30V N+P-CHANNEL ENHANCEMENT MODE MOSFET**
**MAIN CHARACTERISTICS**

$I_D$	18A
$V_{DSS}$	30V
$R_{DS(on)-typ}(@V_{GS}=10V)$	< 22mΩ (Type:15 mΩ)
$I_D$	-15A
$V_{DSS}$	-30V
$R_{DS(on)-typ}(@V_{GS}=-10V)$	< 32mΩ (Type:25 mΩ)


**Application**

- ◆ Wireless charging
- ◆ Boost driver
- ◆ Brushless motor

**Product Specification Classification**

Part Number	Package	Marking	Pack
YFW15G03NF	PDFN5*6-8L	YFW 15G03NF XXXX	5000PCS/Tape

**Maximum Ratings at Tc=25°C unless otherwise specified**

Characteristics	Symbols	Value		Units
		N-Ch	P-Ch	
Drain-Source Voltage	<b>V<sub>DS</sub></b>	30	-30	<b>V</b>
Gate - Source Voltage	<b>V<sub>GS</sub></b>	±20	±20	<b>V</b>
Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup> @T <sub>A</sub> =25°C	<b>I<sub>D</sub></b>	18	-15	<b>A</b>
Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup> @T <sub>A</sub> =100°C	<b>I<sub>D</sub></b>	10	-8	<b>A</b>
Pulsed Drain Current <sup>2</sup>	<b>I<sub>DM</sub></b>	52	-45	<b>A</b>
Single Pulse Avalanche Energy <sup>3</sup>	<b>E<sub>AS</sub></b>	22	45	<b>mJ</b>
Avalanche Current	<b>I<sub>AS</sub></b>	21	-30	<b>A</b>
Total Power Dissipation <sup>4</sup> @T <sub>A</sub> =25°C	<b>P<sub>D</sub></b>	18	18	<b>W</b>
Storage Temperature Range	<b>T<sub>STG</sub></b>	-55 to +150		<b>°C</b>
Operating Junction Temperature Range	<b>T<sub>J</sub></b>	-55 to +150		<b>°C</b>
Thermal Resistance Junction-Ambient <sup>1</sup>	<b>R<sub>θJA</sub></b>	55		<b>°C/W</b>
Thermal Resistance Junction-Ambient <sup>1</sup> , (t<=10sec)	<b>R<sub>θJC</sub></b>	5		<b>°C/W</b>

**N-Channel Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)**

Characteristics	Test Condition	Symbols	Min	Typ	Max	Units
Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250uA	<b>BV<sub>DSS</sub></b>	30	32.5	-	<b>V</b>
Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =10V, I <sub>D</sub> =10A	<b>R<sub>DS(ON)</sub></b>	-	15	22	<b>mΩ</b>
	V <sub>GS</sub> =4.5V, I <sub>D</sub> =5A		-	20	30	<b>mΩ</b>
Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250uA	<b>V<sub>GS(th)</sub></b>	1.0	1.6	2.5	<b>V</b>
Drain-Source Leakage Current	V <sub>DS</sub> =24V, V <sub>GS</sub> =0V, T <sub>J</sub> =25°C	<b>I<sub>DSS</sub></b>	-	-	1	<b>uA</b>
	V <sub>DS</sub> =24V, V <sub>GS</sub> =0V, T <sub>J</sub> =55°C		-	-	5	
Gate-Source Leakage Current	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	<b>I<sub>GSS</sub></b>	-	-	±100	<b>nA</b>
Forward Transconductance	V <sub>DS</sub> = 5V, I <sub>D</sub> =10A	<b>g<sub>fs</sub></b>	-	16	-	<b>S</b>
Gate Resistance	V <sub>DS</sub> =0V, V <sub>GS</sub> =0V, f=1MHz	<b>R<sub>g</sub></b>	-	2.5	5	<b>Ω</b>
Total Gate Charge(4.5V)	V <sub>DS</sub> =20V V <sub>GS</sub> =4.5V I <sub>D</sub> =10A	<b>Q<sub>g</sub></b>	-	7.2	-	<b>nC</b>
Gate-Source Charge		<b>Q<sub>gs</sub></b>	-	1.4	-	
Gate-Drain Charge		<b>Q<sub>gd</sub></b>	-	2.2	-	
Turn-on delay time	V <sub>DD</sub> =15V V <sub>GS</sub> =10V R <sub>G</sub> = 3.3Ω I <sub>D</sub> = 5A	<b>t<sub>d(on)</sub></b>	-	4.1	-	<b>ns</b>
Rise Time		<b>T<sub>r</sub></b>	-	9.8	-	
Turn-Off Delay Time		<b>t<sub>d(OFF)</sub></b>	-	15.5	-	
Fall Time		<b>t<sub>f</sub></b>	-	6.0	-	
Input Capacitance	V <sub>DS</sub> =15V V <sub>GS</sub> =0V f=1MHz	<b>C<sub>iss</sub></b>	-	572	-	<b>pF</b>
Output Capacitance		<b>C<sub>oss</sub></b>	-	81	-	
Reverse Transfer Capacitance		<b>C<sub>rss</sub></b>	-	65	-	
Continuous Source Current <sup>1,5</sup>	V <sub>G</sub> =V <sub>D</sub> =0V, Force Current	<b>I<sub>S</sub></b>	-	-	10	<b>A</b>
Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V, I <sub>S</sub> =1A, T <sub>J</sub> =25°C	<b>V<sub>SD</sub></b>	-	-	1.2	<b>V</b>

Note :

- 1、 The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2、 The data tested by pulsed , pulse width ≅ 300us , duty cycle ≅ 2%
- 3、 The EAS data shows Max. rating . The test condition is V<sub>DD</sub>=25V,V<sub>GS</sub>=10V,L=0.1mH,I<sub>AS</sub>=10A
- 4、 The power dissipation is limited by 150°C junction temperature
- 5、 The data is theoretically the same as I<sub>D</sub> and I<sub>DM</sub> , in real applications , should be limited by total power dissipation.

**P-Channel Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)**

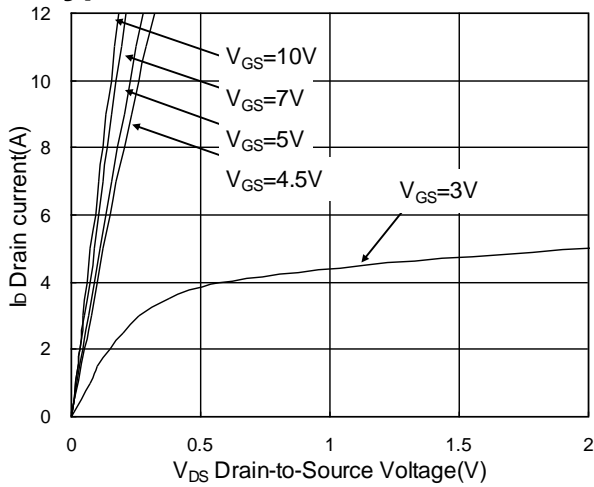
Characteristics	Test Condition	Symbols	Min	Typ	Max	Units
Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =-250uA	<b>BV<sub>DSS</sub></b>	-30	-33	-	<b>V</b>
Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =-10V, I <sub>D</sub> =-7A	<b>R<sub>DS(ON)</sub></b>	-	25	32	<b>mΩ</b>
	V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-5A		-	37	54	<b>mΩ</b>
Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =-250uA	<b>V<sub>GS(th)</sub></b>	-1.0	-	-2.5	<b>V</b>
Drain-Source Leakage Current	V <sub>DS</sub> =-24V, V <sub>GS</sub> =0V, T <sub>J</sub> =25°C	<b>I<sub>DSS</sub></b>	-	-	-1	<b>uA</b>
	V <sub>DS</sub> =-24V, V <sub>GS</sub> =0V, T <sub>J</sub> =55°C		-	-	-5	
Gate-Source Leakage Current	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	<b>I<sub>GSS</sub></b>	-	-	±100	<b>nA</b>
Forward Transconductance	V <sub>DS</sub> = -5V, I <sub>D</sub> =- 7A	<b>g<sub>fs</sub></b>	-	15	-	<b>S</b>
Gate Resistance	V <sub>DS</sub> =0V, V <sub>GS</sub> =0V, f=1MHz	<b>R<sub>g</sub></b>	-	15	30	
Total Gate Charge(-4.5V)	V <sub>DS</sub> =-20V V <sub>GS</sub> =-4.5V I <sub>D</sub> =-7A	<b>Q<sub>g</sub></b>	-	9.8	-	<b>nC</b>
Gate-Source Charge		<b>Q<sub>gs</sub></b>	-	2.2	-	
Gate-Drain Charge		<b>Q<sub>gd</sub></b>	-	3.4	-	
Turn-on delay time	V <sub>DD</sub> =-15V V <sub>GS</sub> =-10V R <sub>G</sub> = 3.3 I <sub>D</sub> =-5A	<b>t<sub>d(on)</sub></b>	-	16.4	-	<b>ns</b>
Rise Time		<b>T<sub>r</sub></b>	-	20.2	-	
Turn-Off Delay Time		<b>t<sub>d(OFF)</sub></b>	-	55	-	
Fall Time		<b>t<sub>f</sub></b>	-	10	-	
Input Capacitance	V <sub>DS</sub> =15V V <sub>GS</sub> =0V f=1MHz	<b>C<sub>iss</sub></b>	-	930	-	<b>pF</b>
Output Capacitance		<b>C<sub>oss</sub></b>	-	148	-	
Reverse Transfer Capacitance		<b>C<sub>rss</sub></b>	-	115	-	
Continuous Source Current <sup>1,5</sup>	V <sub>G</sub> =V <sub>D</sub> =0V, Force Current	<b>I<sub>S</sub></b>	-	-	-8	<b>A</b>
Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V, I <sub>S</sub> =-1A, T <sub>J</sub> =25°C	<b>V<sub>SD</sub></b>	-	-	-1.2	<b>V</b>

Note :

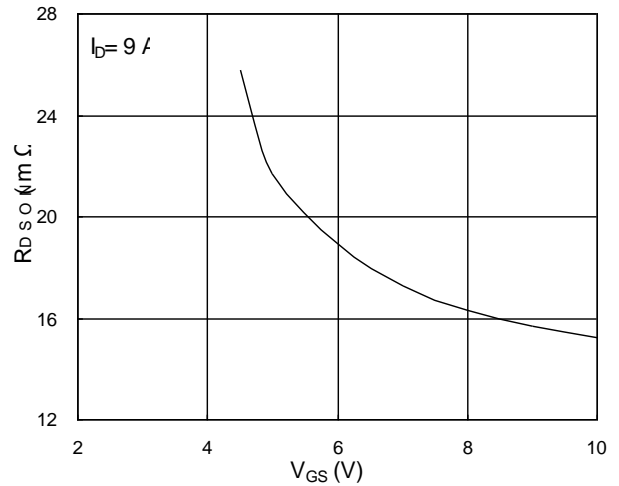
- 1、 The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2、 The data tested by pulsed , pulse width ≅ 300us , duty cycle ≅ 2%
- 3、 The EAS data shows Max. rating . The test condition is V<sub>DD</sub>=-25V, V<sub>GS</sub>=-10V, L=0.1mH, I<sub>AS</sub>=-10A
- 4、 The power dissipation is limited by 150°C junction temperature
- 5、 The data is theoretically the same as I<sub>D</sub> and I<sub>DM</sub> , in real applications , should be limited by total power dissipation.

**Ratings and Characteristic Curves**

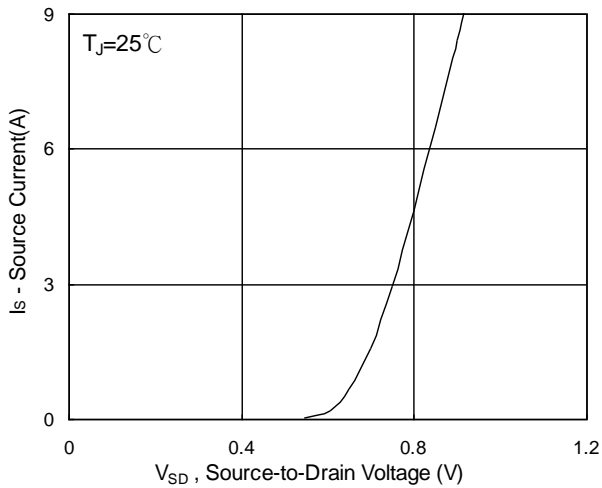
**N-Typical Characteristics**



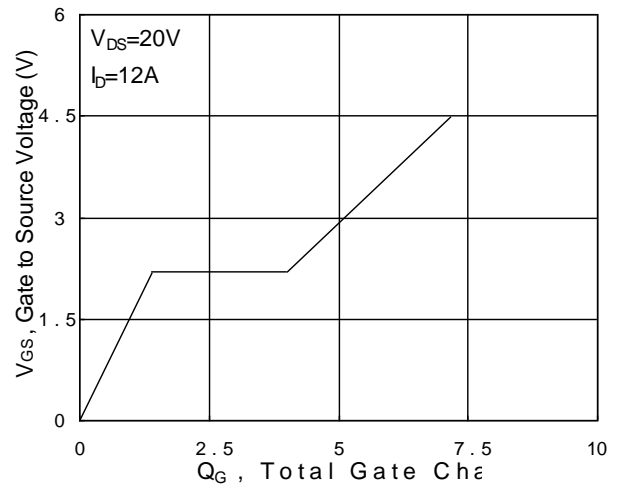
**Fig.1 Typical Output Characteristics**



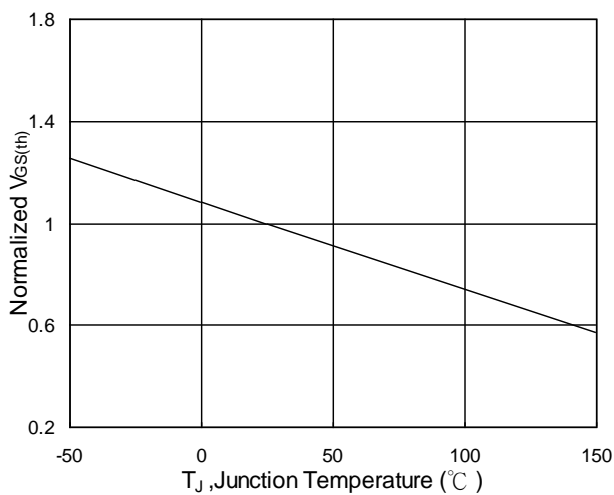
**Fig.2 On-Resistance v.s Gate-Source**



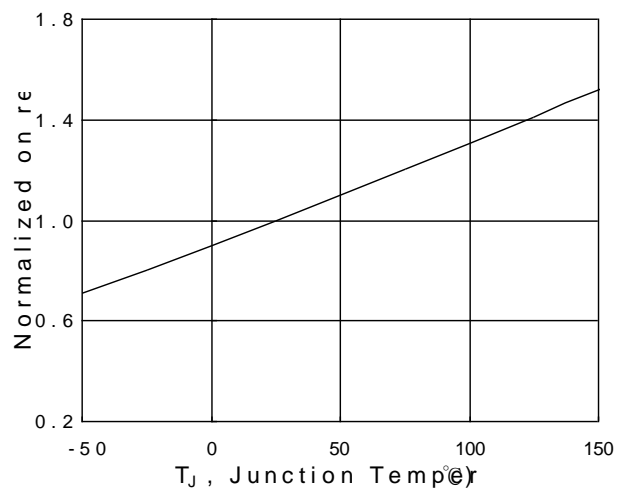
**Fig.3 Forward Characteristics Of Reverse**



**Fig.4 Gate-Charge characteristics**

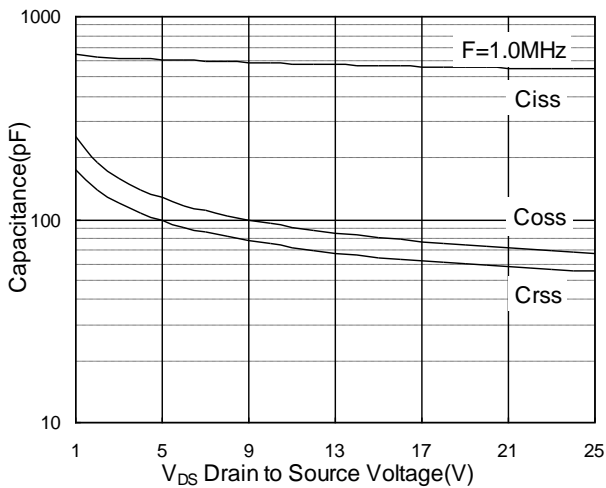


**Fig.5 Normalized  $V_{GS(th)}$  v.s  $T_J$**

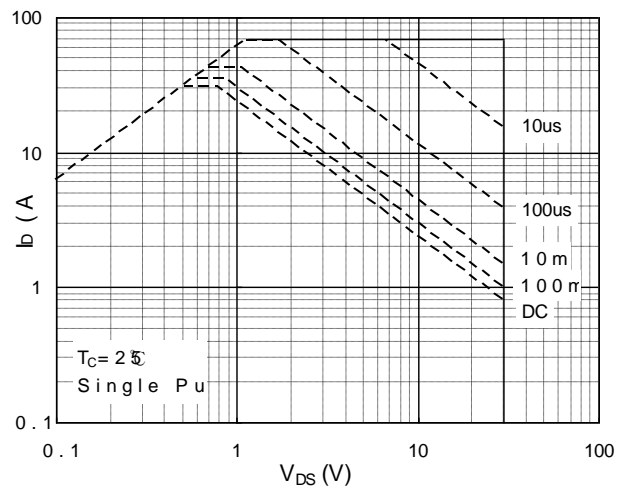


**Fig.6 Normalized  $R_{DS(on)}$  v.s  $T_J$**

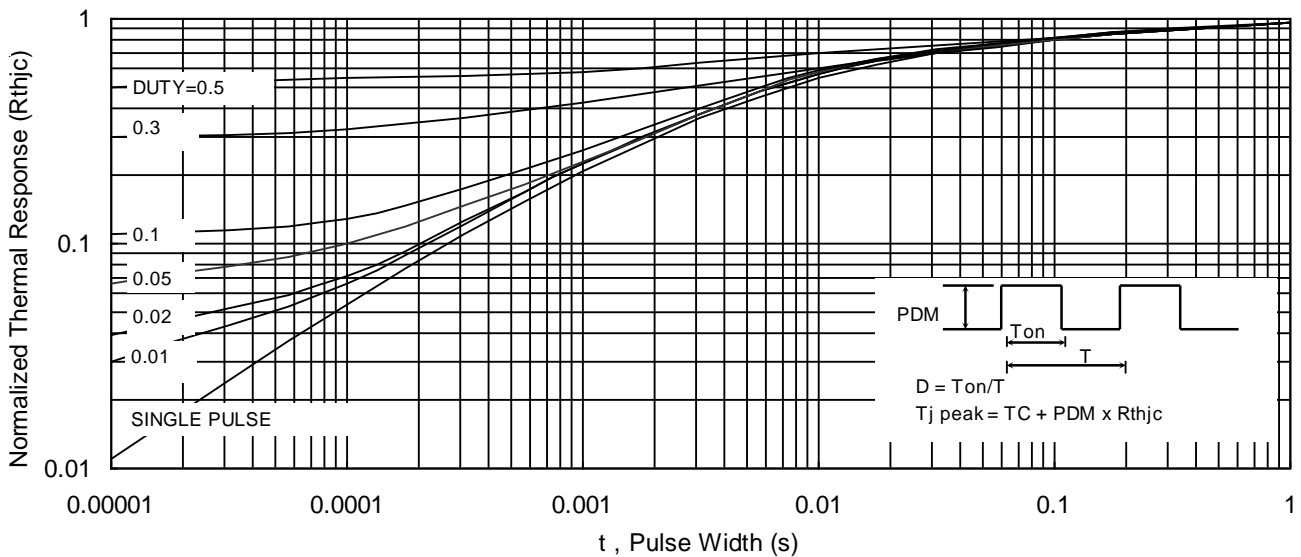
**Ratings and Characteristic Curves**



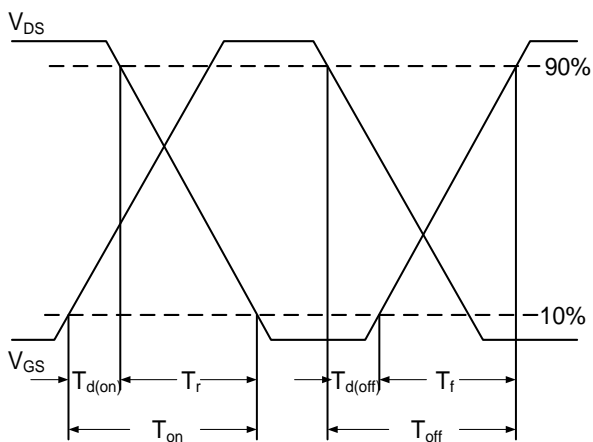
**Fig.7 Capacitance**



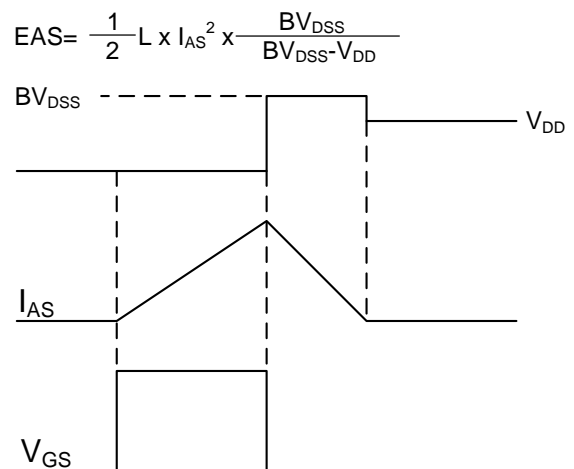
**Fig.8 Safe Operating Area**



**Fig.9 Normalized Maximum Transient Thermal Impedance**



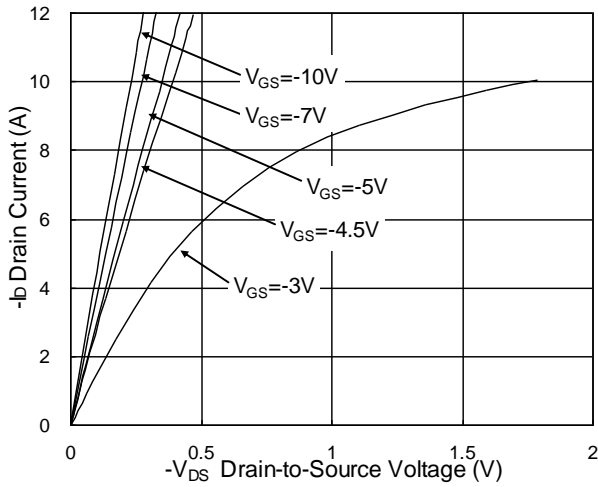
**Fig.10 Switching Time Waveform**



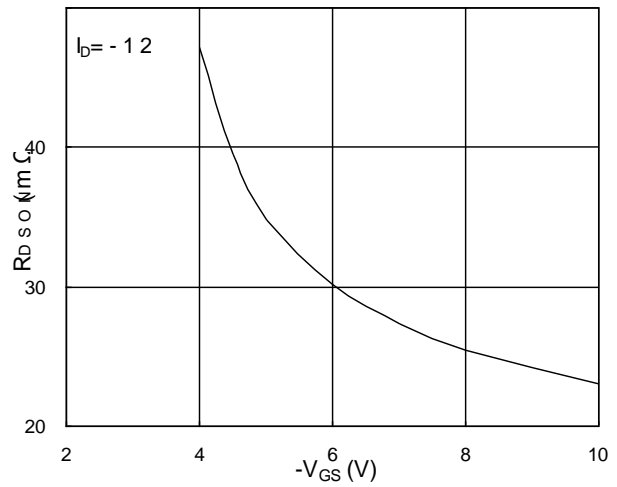
**Fig.11 Unclamped Inductive Waveform**

**Ratings and Characteristic Curves**

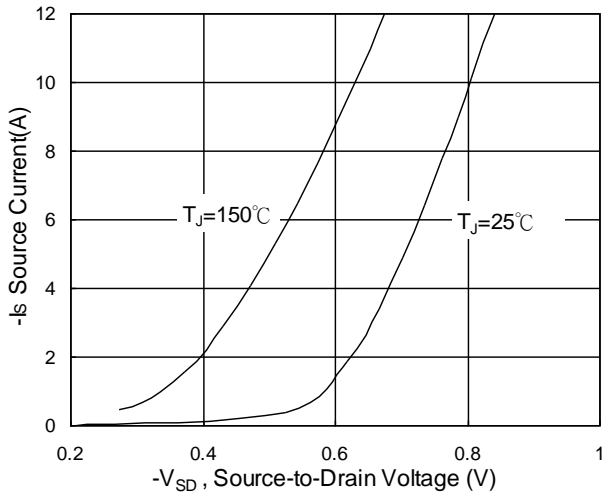
**P-Typical Characteristics**



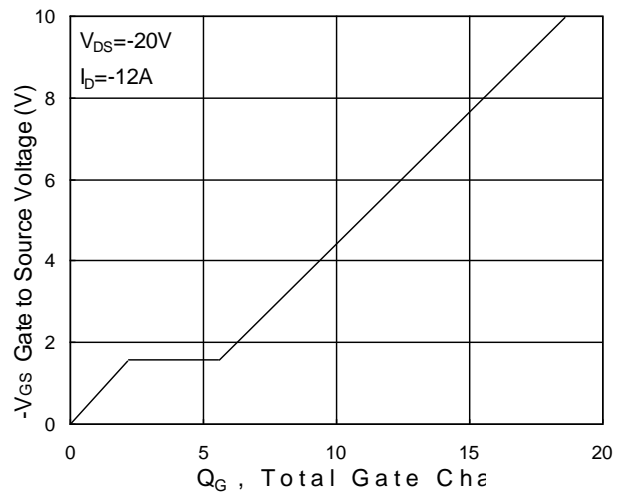
**Fig.1 Typical Output Characteristics**



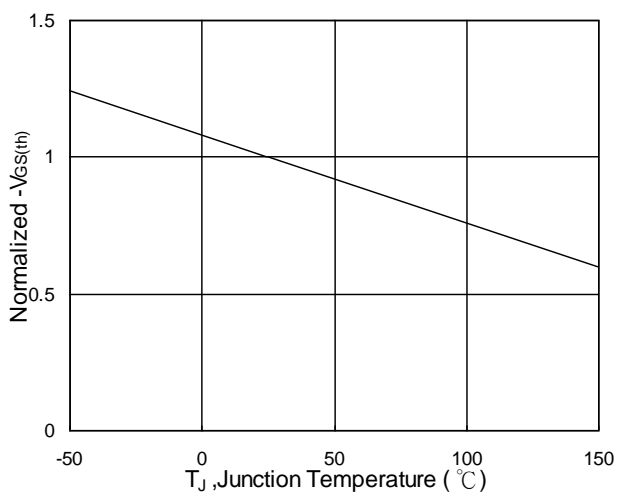
**Fig.2 On-Resistance v.s Gate-Source**



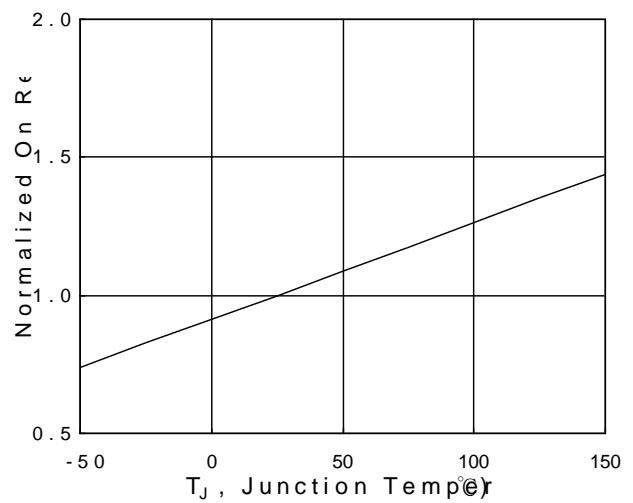
**Fig.3 Forward Characteristics Of Reverse**



**Fig.4 Gate-Charge Characteristics**

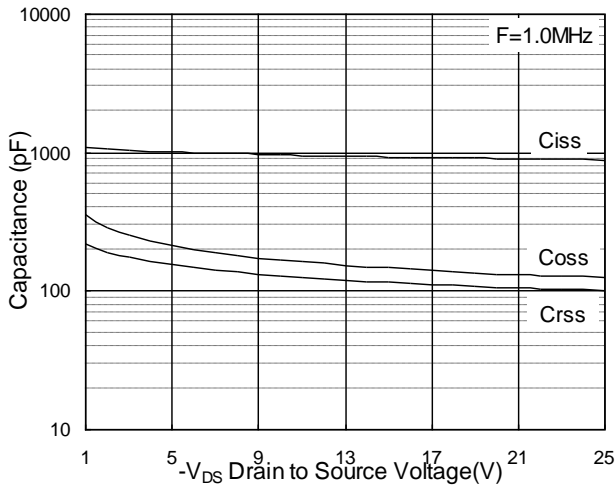


**Fig.5 Normalized  $V_{GS(th)}$  v.s  $T_J$**

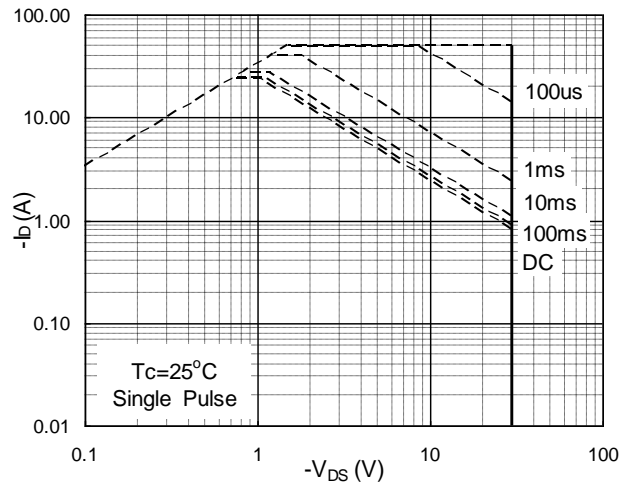


**Fig.6 Normalized  $R_{DS(on)}$  v.s  $T_J$**

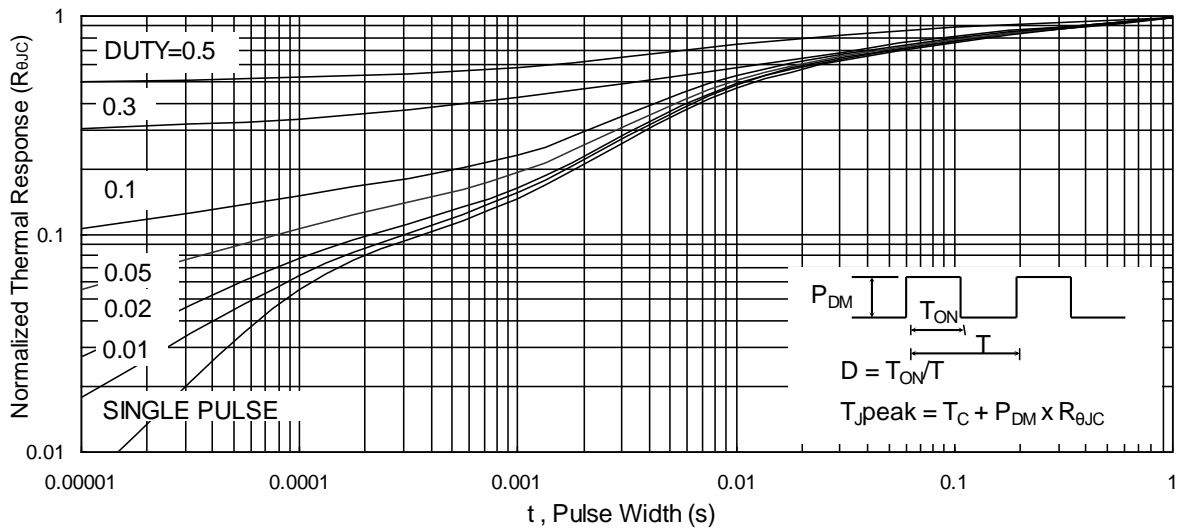
**Ratings and Characteristic Curves**



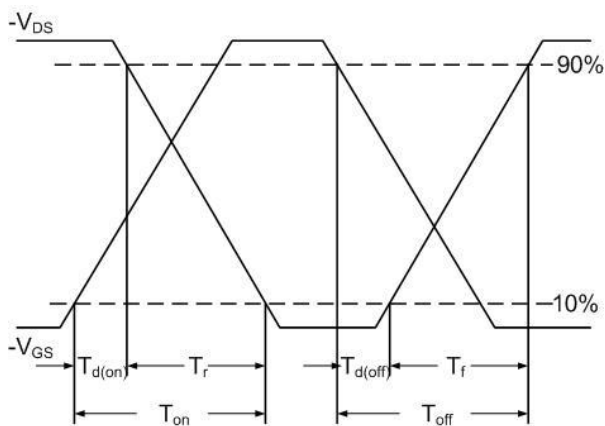
**Fig.7 Capacitance**



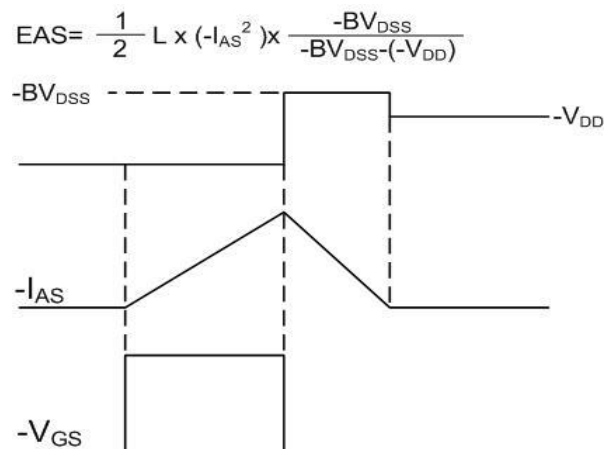
**Fig.8 Safe Operating Area**



**Fig.9 Normalized Maximum Transient Thermal Impedance**

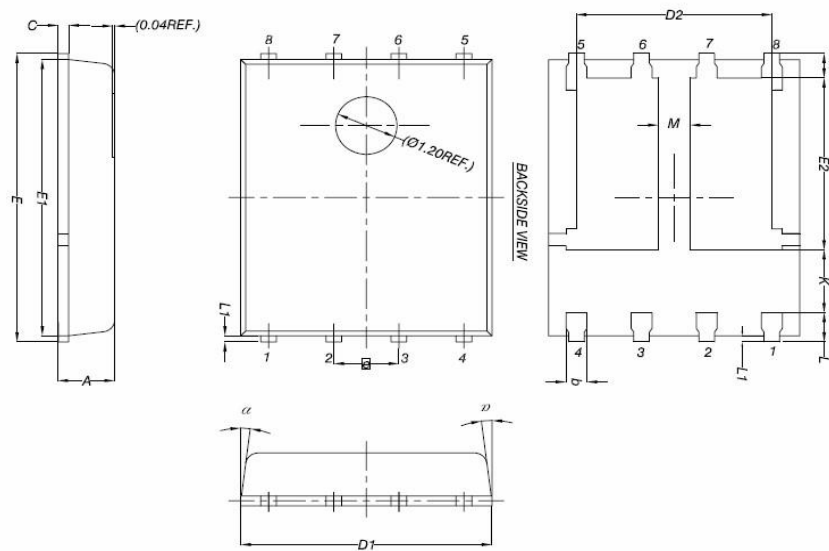


**Fig.10 Switching Time Waveform**



**Fig.11 Unclamped Inductive Waveform**

**PDFN5\*6-8L**



Symbol	Common		
	mm		
	Mim	Nom	Max
A	0.90	1.00	1.10
b	0.33	0.41	0.51
C	0.20	0.25	0.30
D1	4.80	4.90	5.00
D2	3.61	3.81	3.96
E	5.90	6.00	6.10
E1	5.66	5.76	5.83
E2	3.37	3.47	3.58
e	1.27BSC		
H	0.41	0.51	0.61
K	1.10	--	--
L	0.51	0.61	0.71
L1	0.06	0.13	0.20
M	0.50	--	--
a	0°	--	12°